

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0736565000

Status:

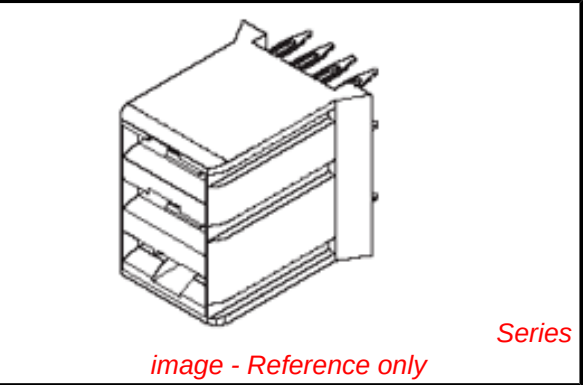
Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits



Documents:

[3D Model](#)

[RoHS Certificate of Compliance \(PDF\)](#)

[Product Specification PS-73670-9999 \(PDF\)](#)

General	
Product Family	Backplane Connectors
Series	73656
Application	Backplane
Comments	Midplane Power Module, Molex Series 73659
Component Type	Power Header
Overview	hdm
Product Name	HDM®
Style	N/A
Physical	
Circuits (Loaded)	3
Circuits (maximum)	3
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.000 In
Pitch - Mating Interface (mm)	0.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	2
Plating min: Termination (µm)	0.05
Polarized to PCB	Yes
Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

EU RoHS

RoHS Compliant by Exemption

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Not Reviewed

China RoHS



Pb

Need more information on product environmental compliance?

Email productcompliance@molex.com

For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

73656Series

Mates With

[73651](#) HDM® Board-to-Board Daughterboard Power Module

Current - Maximum per Contact	15A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	500V AC

Material Info

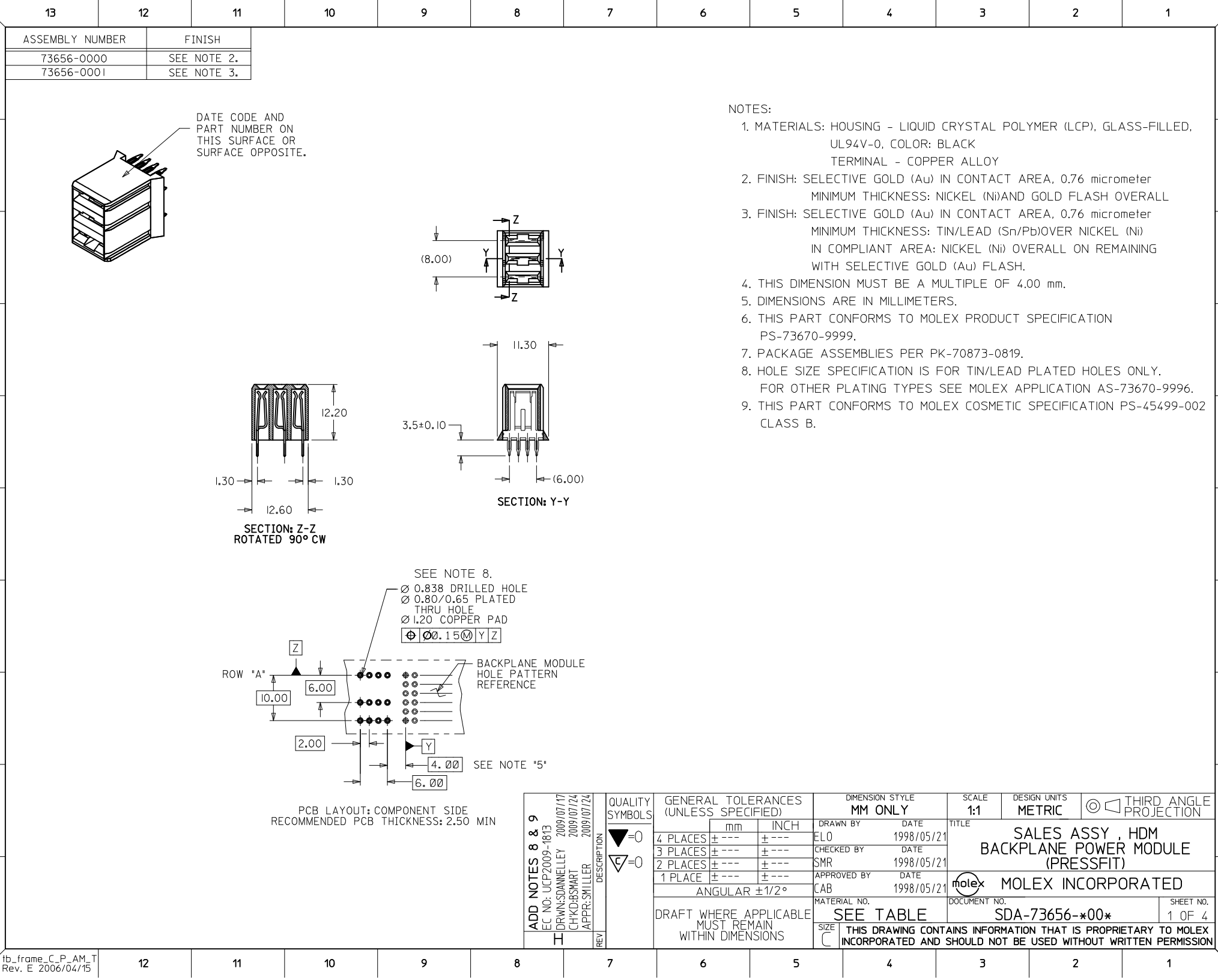
Reference - Drawing Numbers

Application Specification	AS-73656-1998
Packaging Specification	PK-70873-0819
Product Specification	PS-73670-9999
Sales Drawing	SDA-73656-*00*

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This document was generated on 05/14/2010

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F

E

D

C

B

A

F

E

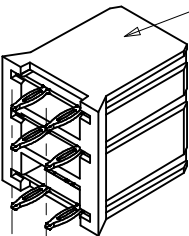
D

C

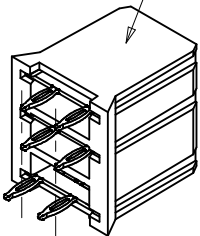
B

A

DATE CODE AND
PART NUMBER ON
THIS SURFACE OR
SURFACE OPPOSITE.



73656-100*

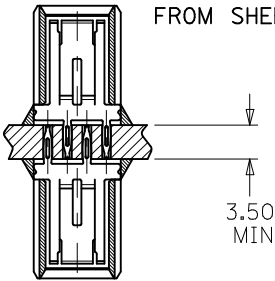


73656-200*

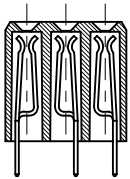
MIDPLANE OPTION

ASSEMBLY NUMBER	FINISH (SEE SHT 1)
73656-1000	SEE NOTE 2. (GOLD TAILS)
73656-2000	
73656-1001	SEE NOTE 3. (TIN/LEAD TAILS)
73656-2001	

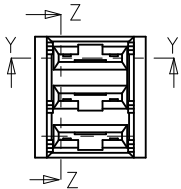
USE BACKPLANE MODULE
HOLE REFERENCE PATTERN
FROM SHEET 1



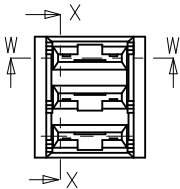
BACK-TO-BACK
MOUNTING APPLICATION



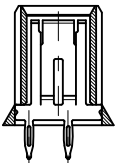
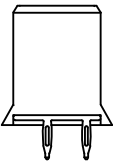
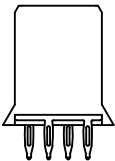
SECTION X-X
SECTION Z-Z
ROTATED 90° CW



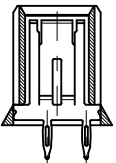
73656-200*



73656-100*



SECTION: Y-Y
(4.00)



SECTION: W-W
(4.00)

SEE SHEET 1 EC NO: UCP2009-1813 DRWN:SDANIELLEY 2009/07/17 CHKD:BSMART 2009/07/24 APPR:SMILLER 2009/07/24	REV DESCRIPTION	QUALITY SYMBOLS ▽=0 C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION 			
									SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		SEE TABLE		DOCUMENT NO. SDA-73656-*00*		SHEET NO. 2 OF 4	
					SIZE B		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

ASSEMBLY NUMBER

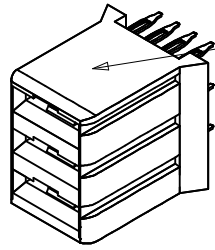
FINISH (SHT I)

73656-5000

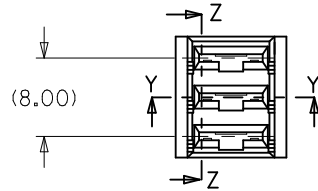
SEE NOTE 2.

73656-5001

SEE NOTE 3.



DATE CODE AND
PART NUMBER ON
THIS SURFACE OR
SURFACE OPPOSITE.



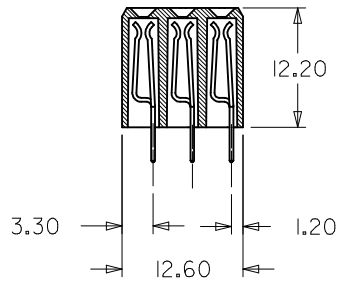
(8.00)

11.30

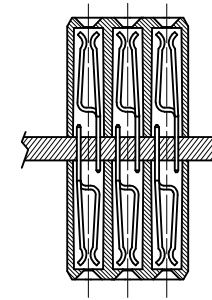
3.5±0.10

(6.00)

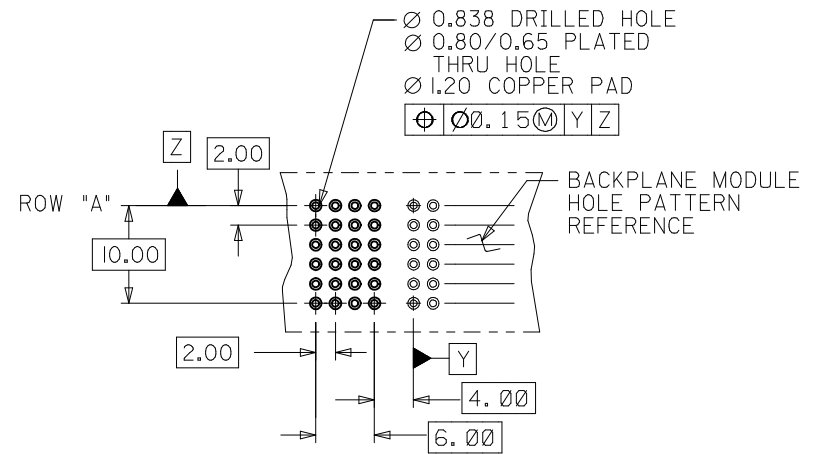
SECTION: Y-Y



SECTION: Z-Z
ROTATED 90° CW



2.36 MIN



Ø 0.838 DRILLED HOLE
Ø 0.80/0.65 PLATED
THRU HOLE
Ø 1.20 COPPER PAD

⌀ Ø0.15(M) Y Z

BACKPLANE MODULE
HOLE PATTERN
REFERENCE

GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY	DATE	TITLE	
4 PLACES	± ---	± ---	± ---	ELO	1998/05/21	SALES ASSY, HDM BACKPLANE POWER MODULE (PRESSFIT) MOLEX INCORPORATED	
3 PLACES	± ---	± ---	± ---	CHECKED BY	DATE		
2 PLACES	± ---	± ---	± ---	SMR	1998/05/21		
1 PLACE	± ---	± ---	± ---	APPROVED BY	DATE		
ANGULAR ±1/2°				CAB	1998/05/21		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MATERIAL NO.		DOCUMENT NO.	SHEET NO.
		SIZE B		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SDA-73656-*00*	3 OF 4

ASSEMBLY NUMBER

FINISH

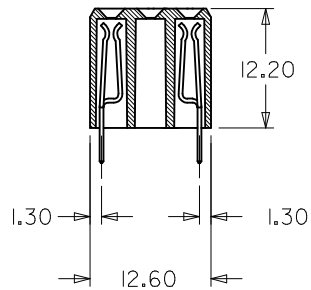
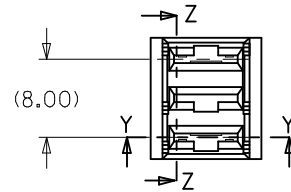
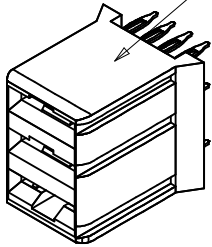
73656-0180

SEE NOTE 2.

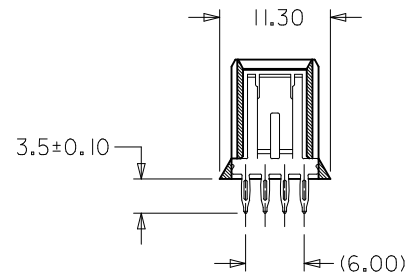
73656-0181

SEE NOTE 3.

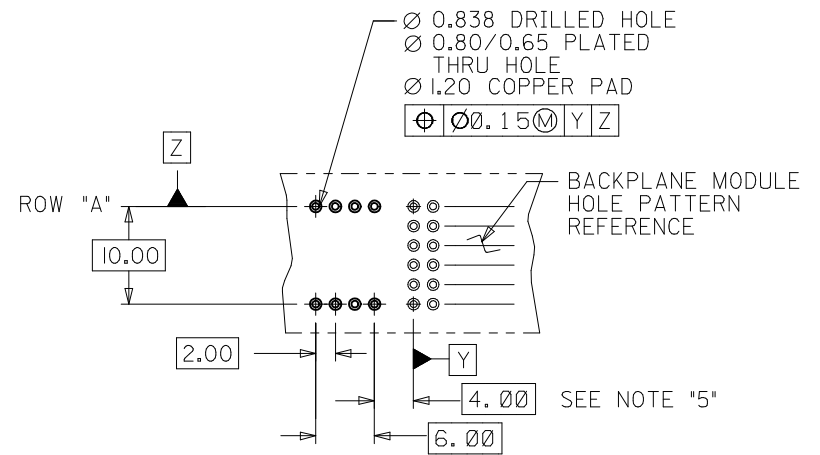
DATE CODE AND
PART NUMBER ON
THIS SURFACE OR
SURFACE OPPOSITE.



SECTION: Z-Z
ROTATED 90° CW

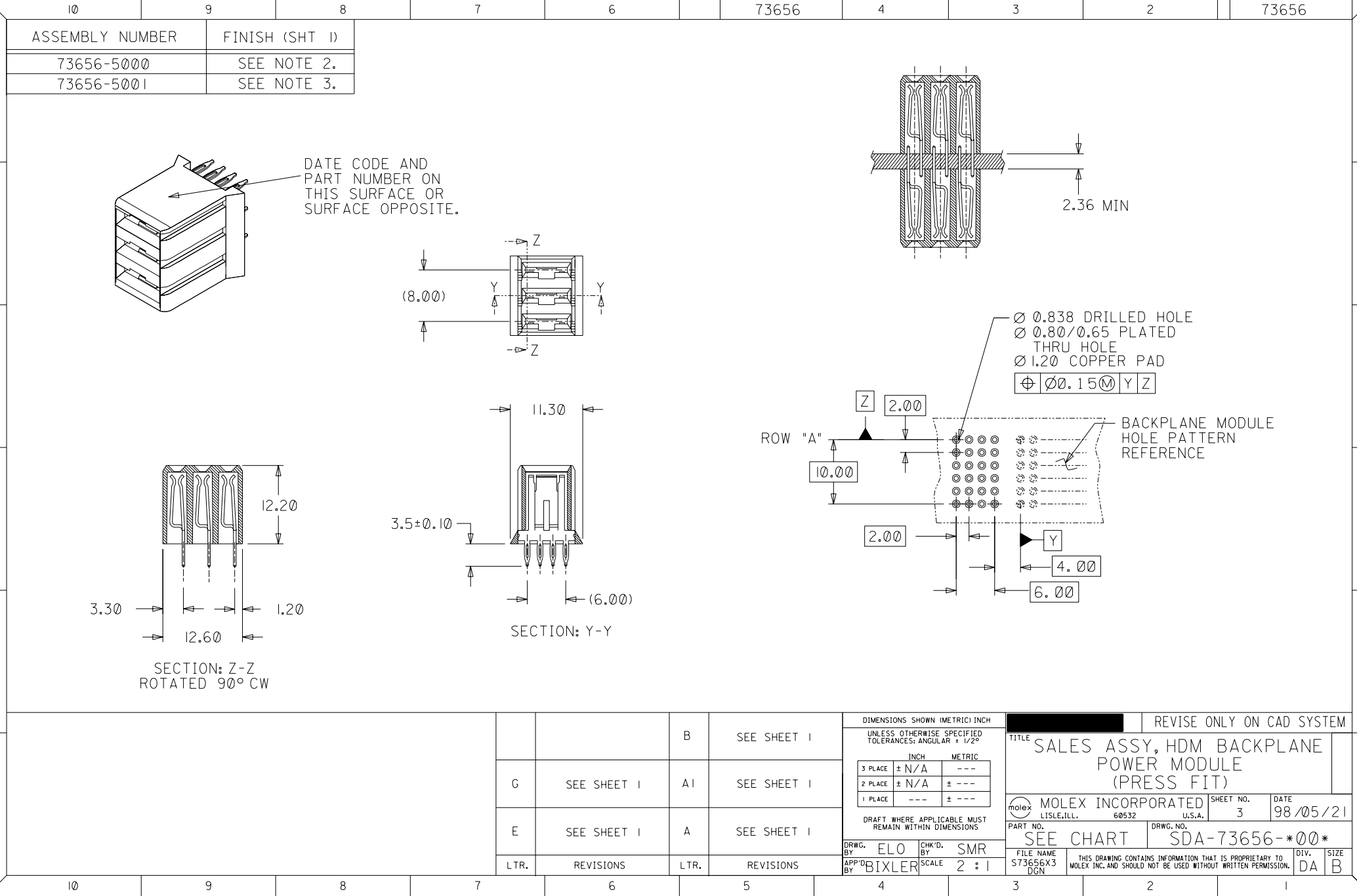


SECTION: Y-Y



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

SEE SHEET 1 EC NO: UCP2009-1813 DRAWN:SDANIELLEY 2009/07/17 CHKD:SMART 2009/07/24 APPR:SMILLER 2009/07/24	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY	DATE	TITLE SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)				
			4 PLACES	± ---	± ---	ELO	1998/05/21					
			3 PLACES	± ---	± ---	CHECKED BY	DATE					
			2 PLACES	± ---	± ---	SMR	1998/05/21	MOLEX MOLEX INCORPORATED				
			1 PLACE	± ---	± ---	APPROVED BY	DATE					
			ANGULAR ±1/2°			CAB	1998/05/21	MOLEX MOLEX INCORPORATED				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO. SEE TABLE		DOCUMENT NO. SDA-73656-*00*							
REV	H		SIZE B		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



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<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

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